

HVC362

Variable Capacitance Diode for VCO

REJ03G0086-0100Z (Previous: ADE-208-456)

Rev.1.00

Sep.17.2003

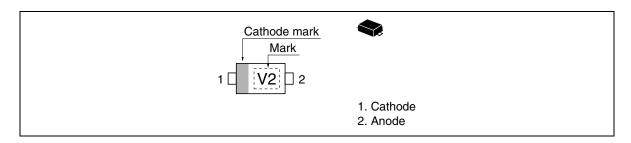
Features

- High capacitance ratio. (n = 3.0.min)
- Good C-V linearity.
- Ultra small Flat Package (UFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVC362	V2	UFP

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	$V_{_{\mathrm{R}}}$	15	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	−55 to +125	°C

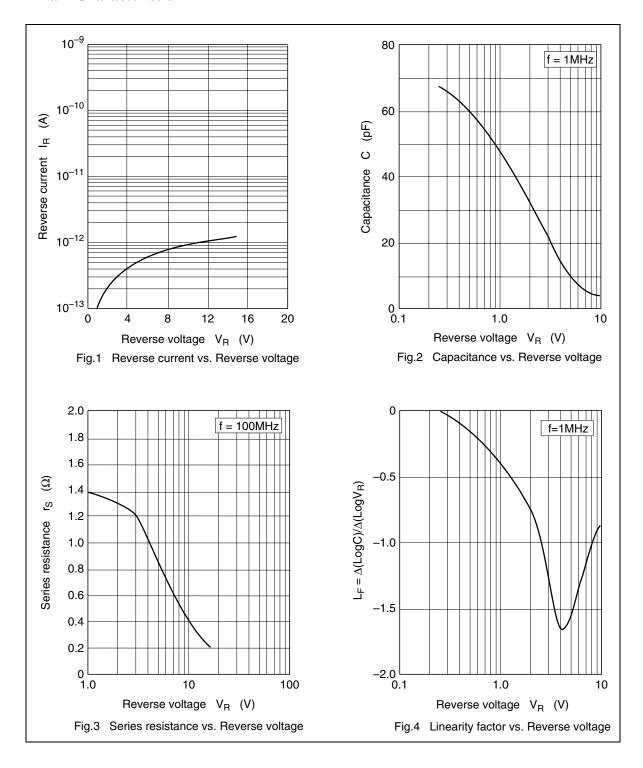
Electrical Characteristics

 $(Ta = 25^{\circ}C)$

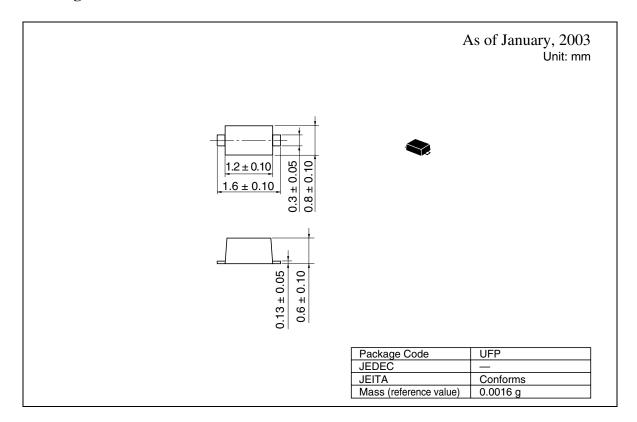
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _{R1}	_	_	10	nA	V _R = 10 V
	I _{R2}	_	_	100	_	V _R = 10 V, Ta = 60°C
Capacitance	C ₁	41.6	_	49.9	pF	V _R = 1 V, f = 1 MHz
	C ₄	10.1	_	14.8		V _R = 4 V, f = 1 MHz
Capacitance ratio	n	3.0	_	_	_	C ₁ /C ₄
Series resistance	r _s	_	_	2.0	Ω	V _R = 4 V, f = 100 MHz
ESD-Capability *1	_	80	_	_	V	C = 200 pF, Both forward and reverse direction 1 pulse.

Note: 1. Failure criterion; $I_R \ge 20 \text{ nA}$ at $V_R = 10 \text{ V}$

Main Characteristic



Package Dimensions



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Renesas Technology America, Inc. 450 Holger Way, San Jose, CA 95134-1368, U.S.A Tel: <1> (408) 382-7500 Fax: <1> (408) 382-7501

Renesas Technology Europe Limited.

Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, United Kingdom Tel: <44> (1628) 585 100, Fax: <44> (1628) 585 900

Renesas Technology Europe GmbH Dornacher Str. 3, D-85622 Feldkirchen, Germany Tel: <49> (89) 380 70 0, Fax: <49> (89) 929 30 11

Renesas Technology Hong Kong Ltd. 7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Hong Kong Tel: <852> 2265-6688, Fax: <852> 2375-6836

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Renesas Technology (Shanghai) Co., Ltd. 26/F., Ruijin Building, No.205 Maoming Road (S), Shanghai 200020, China Tel: <86> (21) 6472-1001, Fax: <86> (21) 6415-2952

Renesas Technology Singapore Pte. Ltd.
1, Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632 Tel: <65> 6213-0200, Fax: <65> 6278-8001